ABSTRACT

BGA DEVICE POSITIONER KIT

An apparatus was described which allows accurate and fast positioning of device kits for the input shuttle, the output shuttle, the docking plates, hot plate and testing stations within the semiconductor device manufacturing and testing applications for Ball Grid Array sockets. A method was highlighted by means of which the sockets in these shuttles and plates can be adapted to different sizes and different types of semiconductor devices. A pick up shaft described resulted in added flexibility within the semiconductor device manufacturing and testing environment.

(FIGURE 1a IS SUGGESTED FOR PUBLICATION)